

Applicable standard							
Rating	Operating temperature range	-35 °C to +85 °C (Note1)		Storage temperature range		-10 °C to +60 °C (Note3)	
	Operating humidity range	40% to 80% (Note2)		Storage humidity range		40% to 70% (Note3)	
	Voltage	250 V AC		Applicable connector		DF1E-*S-2. 5C	
	Current	AWG20 to 24: 3A AWG26: 2A AWG28: 1A AWG30: 0. 5A		UL, CSA	Voltage	AC 30V	
		Current	AWG20 to 22: 3A AWG24 to 28: 1A AWG30: 0. 5A				
Specifications							
Item		Test method		Requirements		QT	AT
Construction							
General examination		Visually and by measuring instrument.		According to drawing.		X	X
Marking		Confirmed visually.				X	X
Electric characteristics							
Contact resistance millivolt level method.		20 mV MAX, 1 mA(DC or 1000 Hz).		30 mΩ MAX.		X	—
Insulation resistance		500 V DC.		1000 MΩ MIN.		X	—
Voltage proof		650 V AC for 1 min.		No flashover or breakdown.		X	—
Mechanical characteristics							
Mechanical operation		30times insertions and extractions.		① Contact resistance: 30 mΩ MAX. ② No damage, crack or looseness of parts.		X	—
Vibration		Frequency 10 to 55 Hz, single amplitude 0.75 mm, at 2 h, for 3 directions.		① No electrical discontinuity of 1 μs. ② No damage, crack or looseness of parts.		X	—
Shock		490 m/s ² duration of pulse 11 ms at 3 times for 3 directions.				X	—
Environmental characteristics							
Rapid change of temperature		Temperature -55→ 5 to 35→+85→ 5 to 35 °C Time 30→ 5 max→ 30→ 5 max min Under 5 cycles.		① Contact resistance: 30 mΩ MAX. ② Insulation resistance: 1000 MΩ MIN. ③No damage, crack or looseness of parts.		X	—
Damp heat (Steady state)		Exposed at 40 ± 2 °C, 90 to 95 %, 96 h.		① Contact resistance: 30 mΩ MAX. ② Insulation resistance: 500 MΩ MIN. ③No damage, crack or looseness of parts.		X	—
Resistance to soldering heat		1) Automatic soldering (flow) Solder temperature, 260 °C for Immersion,duration, 10 sec. 2) Manual soldering Soldering iron temperature : 300 °C, Soldering time : 3 sec. No strength on contact.		No deformation of case of excessive looseness of the terminals.		X	—
Solderability		Soldered at solder temperature, 235 °C for insertion duration, 5 s.		Solder shall cover a minimum of 95 % of the surface being immersed.		X	—
Remarks							
Note1: Include the temperature rising by current.							
Note2:No condensing.							
Note3:Apply to the condition of long term storage for unused products before pcb on board. After pcb board,operating temperature and humidity range is applied for interim storage during transportation.							
	Count	Description of revisions	Designed		Checked		Date
△							
Unless otherwise specified, refer to IEC 60512.				Approved	KI. AKIYAMA	15. 06. 16	
				Checked	KI. AKIYAMA	15. 06. 16	
				Designed	TS. KUMAZAWA	15. 06. 15	
				Drawn	MI. SAKIMURA	15. 06. 15	
Note QT:Qualification Test AT:Assurance Test X:Applicable Test			Drawing no.		ELC-336779-35-00		
HRS	Specification sheet		Part no.		DF1EG-*P-2. 5DSA (35)		
	Hirose electric co., ltd.		Code no.		CL541		△ 1/1